

Maintenance type - not for new designs

## MICROWAVE LINEAR POWER TRANSISTOR

NPN silicon transistor for use in common-emitter class-A linear amplifiers up to 4 GHz.

Diffused emitter ballasting resistors, self-aligned process entirely ion implanted and gold sandwich metallization ensure an optimum temperature profile with excellent performance and reliability.

### QUICK REFERENCE DATA

RF performance up to  $T_{mb} = 25\text{ }^{\circ}\text{C}$  in an unneutralized common-emitter class-A circuit

mode of operation	f GHz	V <sub>CE</sub> V	I <sub>C</sub> mA	P <sub>L1</sub> mW	G <sub>p0</sub> dB
c.w.; linear amplifier	4	18	30	typ. 200	typ. 8

### MECHANICAL DATA

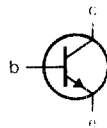
Dimensions in mm

Fig. 1 FO-41B.

Emitter and metallic cap connected to the seating plane.

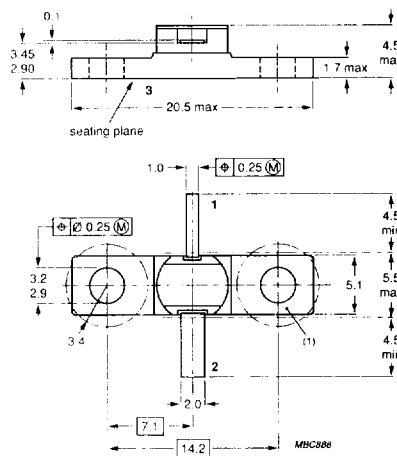
#### Pinning:

- 1 = collector
- 2 = base
- 3 = emitter



Torque on screw: max. 0,5 Nm  
Recommended screw: M2,5

Marking code: 4002S = LTE4002S



(1) Flatness of this area ensures full thermal contact with bolt head.

### WARNING

#### Product and environmental safety – toxic materials

This product contains beryllium oxide. The product is entirely safe provided that the BeO slab is not damaged. All persons who handle, use or dispose of this product should be aware of its nature and of the necessary safety precautions.

After use, dispose of as chemical or special waste according to the regulations applying at the location of the user. It must never be thrown out with general industrial or domestic waste.

## RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC 134)

Collector-base voltage (open emitter)	$V_{CBO}$	max.	40 V
Collector-emitter voltage	$V_{CEO}$	max.	16 V
open base	$V_{CER}$	max.	35 V
$R_{BE} = 220 \Omega$	$V_{EBO}$	max.	3 V
Emitter-base voltage (open collector)	$I_C$	max.	90 mA
Collector current (DC)	$P_{tot}$	max.	1 W
Total power dissipation up to $T_{mb} = 75 \text{ }^\circ\text{C}$	$T_{stg}$		-65 to +200 $^\circ\text{C}$
Storage temperature range	$T_j$	max.	200 $^\circ\text{C}$
Junction temperature	$T_{sld}$	max.	235 $^\circ\text{C}$
Lead soldering temperature			
at 0.3 mm from the case; $t_{sld} \leq 10 \text{ s}$			

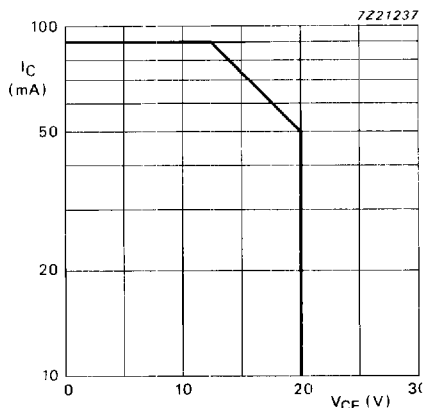


Fig. 2 DC SOAR at  $T_{mb} \leq 75 \text{ }^\circ\text{C}$ ;  $R_{BE} < 220 \Omega$ .

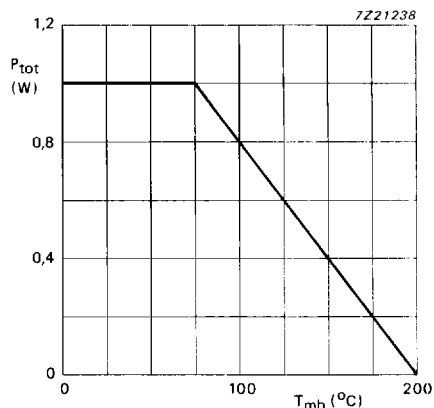


Fig. 3 Power derating curve.

## THERMAL RESISTANCE (at $T_j = 75 \text{ }^\circ\text{C}$ )

From junction to mounting base

$$R_{th \text{ j-mb}} = 45 \text{ K/W}$$

## CHARACTERISTICS

$T_{mb} = 25 \text{ }^\circ\text{C}$ ; unless otherwise specified

Collector cut-off currents

$$I_E = 0; V_{CB} = 20 \text{ V}$$

$$I_{CBO} < 100 \text{ nA}$$

$$I_E = 0; V_{CB} = 40 \text{ V}$$

$$I_{CBO} < 150 \mu\text{A}$$

$$V_{BC} = 35 \text{ V}; R_{BE} = 200 \Omega$$

$$I_{CER} < 500 \mu\text{A}$$

Emitter cut-off currents

$$I_C = 0; V_{EB} = 1,5 \text{ V}$$

$$I_{EBO} < 50 \text{ nA}$$

DC current gain

$$I_C = 30 \text{ mA}; V_{CE} = 5 \text{ V}$$

$$h_{FE} \quad 15 \text{ to } 150$$